

To all our customers

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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

Cautions

Keep safety first in your circuit designs!

1. Renesas Technology Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage.

Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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2SB566(K), 2SB566A(K)

Silicon PNP Triple Diffused

RENESAS

ADE-208-855 (Z)
1st. Edition
September 2000

Application

Low frequency power amplifier power switching complementary pair with 2SD476(K) and 2SD476A(K)

Outline

TO-220AB



1. Base
2. Collector (Flange)
3. Emitter

2SB566(K), 2SB566A(K)

Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings		Unit
		2SB566(K)	2SB566A(K)	
Collector to base voltage	V_{CBO}	-70	-70	V
Collector to emitter voltage	V_{CEO}	-50	-60	V
Emitter to base voltage	V_{EBO}	-5	-5	V
Collector current	I_C	-4	-4	A
Collector peak current	$I_{C(peak)}$	-8	-8	A
Collector power dissipation	P_C^{*1}	40	40	W
Junction temperature	T_j	150	150	°C
Storage temperature	T_{stg}	-55 to +150	-55 to +150	°C

Note: 1. Value at $T_C = 25^\circ\text{C}$.

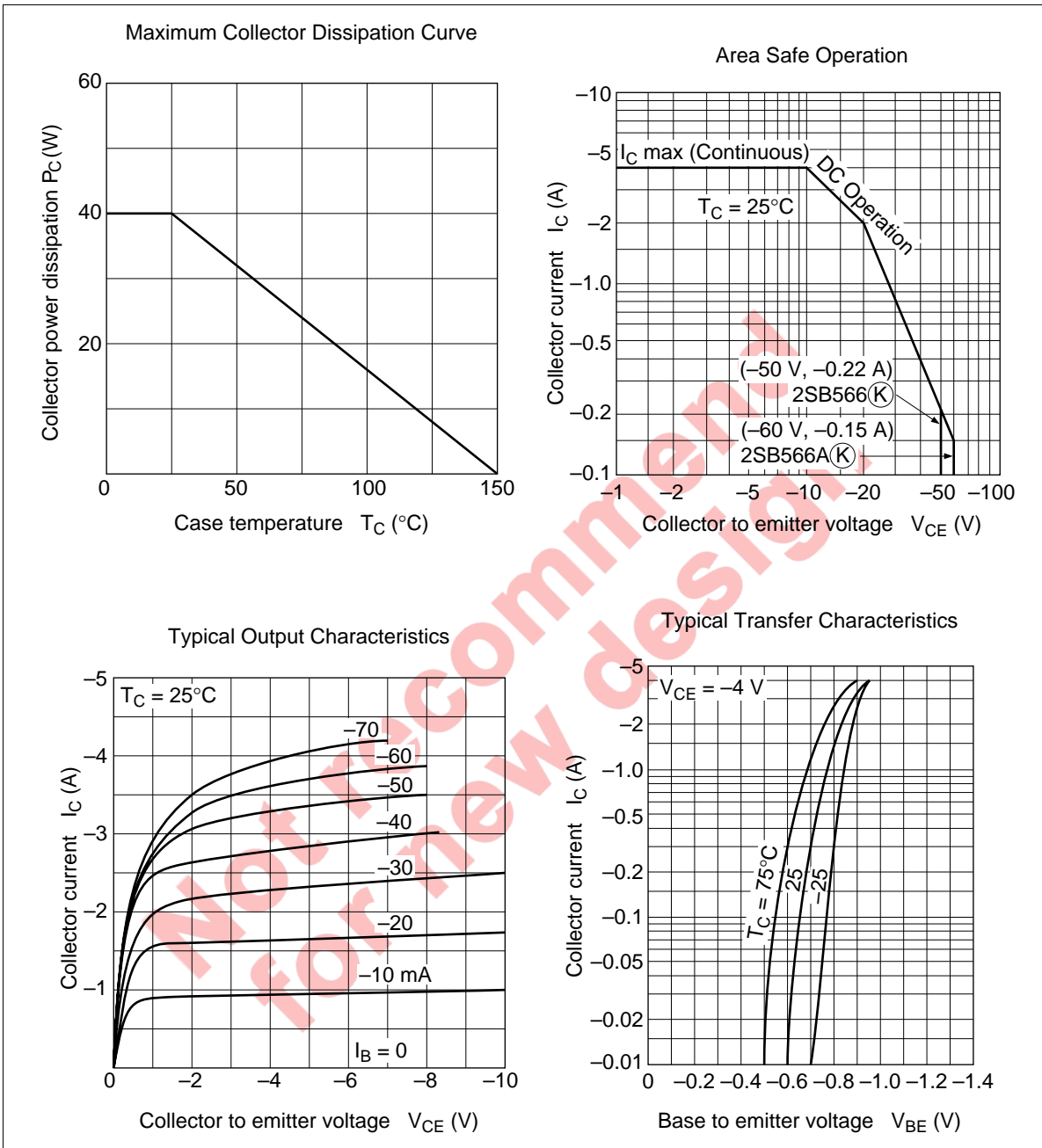
Electrical Characteristics (Ta = 25°C)

Item	Symbol	2SB566(K)			2SB566A(K)			Unit	Test conditions
		Min	Typ	Max	Min	Typ	Max		
Collector to base breakdown voltage	$V_{(BR)CBO}$	-70	—	—	-70	—	—	V	$I_C = -10 \mu\text{A}, I_E = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	-50	—	—	-60	—	—	V	$I_C = -50 \text{ mA}, R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	-5	—	—	-5	—	—	V	$I_E = -10 \mu\text{A}, I_C = 0$
Collector cutoff current	I_{CBO}	—	—	-1	—	—	-1	μA	$V_{CB} = -50 \text{ V}, I_E = 0$
DC current transfer ratio	h_{FE1}^{*1}	60	—	200	60	—	200		$V_{CE} = -4 \text{ V}, I_C = -1 \text{ A}$
	h_{FE2}	35	—	—	35	—	—		$V_{CE} = -4 \text{ V}, I_C = -0.1 \text{ A}$
Collector to emitter saturation voltage	$V_{CE(sat)}$	—	—	-1.0	—	—	-1.0	V	$I_C = -2 \text{ A}, I_B = -0.2 \text{ A}$
Base to emitter saturation voltage	$V_{BE(sat)}$	—	—	-1.2	—	—	-1.2	V	$I_C = -2 \text{ A}, I_B = -0.2 \text{ A}$
Gain bandwidth product	f_T	—	15	—	—	15	—	MHz	$V_{CE} = -4 \text{ V}, I_C = -0.5 \text{ A}$
Turn on time	t_{on}	—	0.3	—	—	0.3	—	μs	$V_{CC} = -10.5 \text{ V}$
Turn off time	t_{off}	—	3.0	—	—	3.0	—	μs	$I_C = 10I_{B1} = -10I_{B2} =$
Storage time	t_{stg}	—	2.5	—	—	2.5	—	μs	-0.5 A

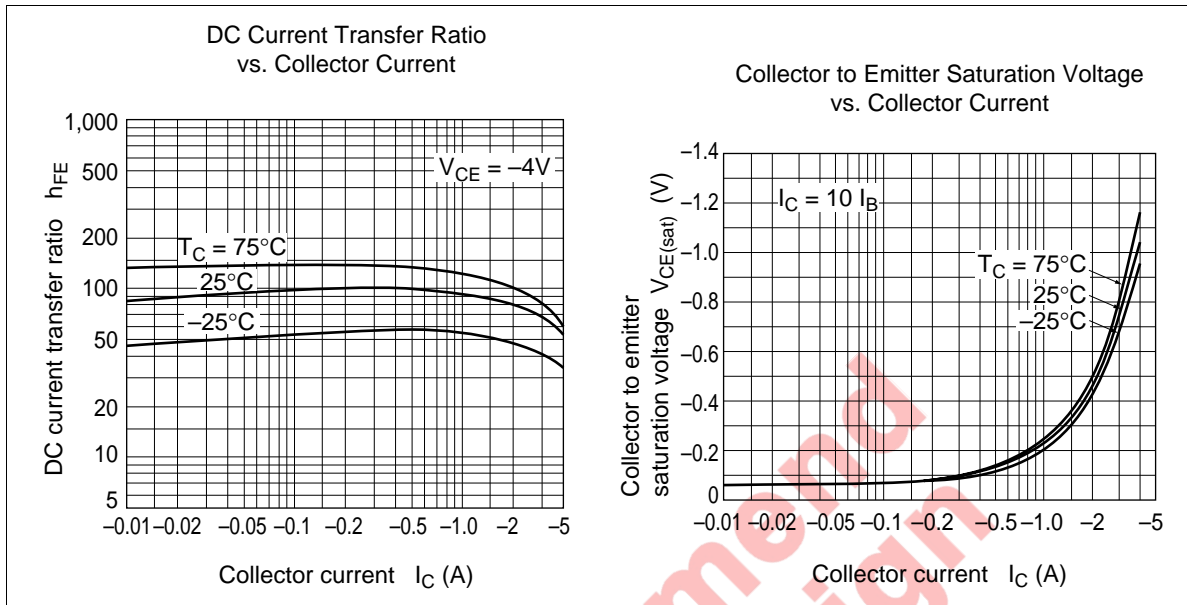
Note: 1. The 2SB566(K) and 2SB566A(K) are grouped by h_{FE1} as follows.

B	C
60 to 120	100 to 200

2SB566(K), 2SB566A(K)



2SB566(K), 2SB566A(K)



Not recommended for new designs

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